

.062" PITCH COMPLIANT PIN HD Stacker™



Solder-free, rugged board-to-board stackable connectors

PERFORMANCE SPECIFICATIONS

Current rating: 3 Amp
 DWV: 638 VAC sea level
 Insulation resistance:
 5000 Megohms minimum @ 500 VDC
 Contact resistance: 3 – 5 Milliohms
 Operating temperature: -65°C to +200°C
 Connector mating force (max):
 (4 ounces) X (number of contacts)
 Press-fit contact insertion force (max):
 (22.5 pounds) X (number of contacts)
 Durability: 500 mating cycles
 Contact wipe: .050" minimum
 (.150" @ max insertion)

MATERIALS AND FINISHES

Insulator: Polyphenylene sulfide (PPS); meets
 NASA outgassing requirements.
 Contacts: Copper alloy, gold (50 to 100
 microinches thick) over nickel (50 to 100
 microinches thick) plating
 Hardware: Copper alloy, nickel plated and/or 300
 series stainless steel, passivated.
 Encapsulant: Epoxy resin Hysol EE4215



PCB REQUIREMENTS

Board material: FR-4, Polyimide, or equivalent
 Board thickness: .058" minimum
 Drilled hole size: Ø.033" (#66 drill)
 Plating material: Sn alloy or ENIG recommended
 Total plating thickness: .001" – .002"

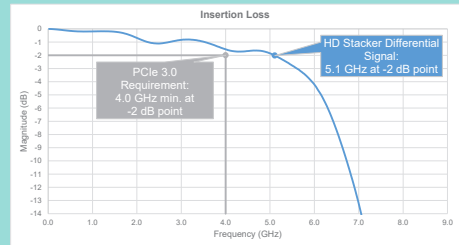
QUALIFICATION TESTING / HIGH-SPEED PERFORMANCE

HD Stacker connectors were qualified in accordance with MIL-DTL-55302G testing for:

- Contact engagement/separation and retention
- DWV
- Electrical resistance
- Mechanical vibration/shock
- Insulation resistance
- Thermal shock
- Contact resistance
- Contact wipe - .150" min
- Humidity

High-frequency electrical performance tests were performed for: Insertion loss, return loss, crosstalk, and time domain performance metrics including impedance and eye pattern.

Complete test reports are available at www.glenair.com/technical_information_test_reports



HD Stacker insertion loss compared to PCIe Rev. 3

PCB LAYOUTS (COMPONENT SIDE)

